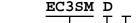
EC3SMD-12-4.194M





Series _____ 4.0mm Epoxy Base SMD Crystal

Mode of Operation -AT-Cut Fundamental

ECTRIC			CATIC	
-0.1810	AL SE	4 E U I E I		

Nominal Frequency	4.194MHz
Frequency Tolerance/Stability	±30ppm at 25°C, ±50ppm over -20°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	200 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatts Maximum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

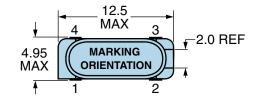
-12 -4.194M

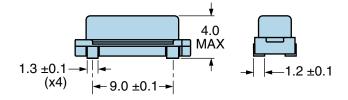
Load Capacitance 12pF Parallel Resonant

4.194MHz

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014 Condition A	
Gross Leak Test	MIL-STD-883, Method 1014 Condition C	
Mechanical Shock	MIL-STD-202, Method 213 Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007 Condition A	

MECHANICAL DIMENSIONS (all dimensions in millimeters)





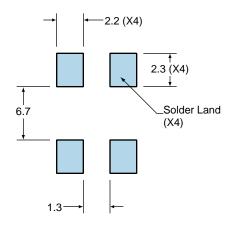
PIN	CONNECTION
1	Crystal
2	Connected to Pin 3
3	Connected to Pin 2
4	Crystal
LINE	MARKING
1 E4.194 <i>E=Ecliptek Designator</i>	

EC3SMD-12-4.194M



Suggested Solder Pad Layout

All Dimensions in Millimeters

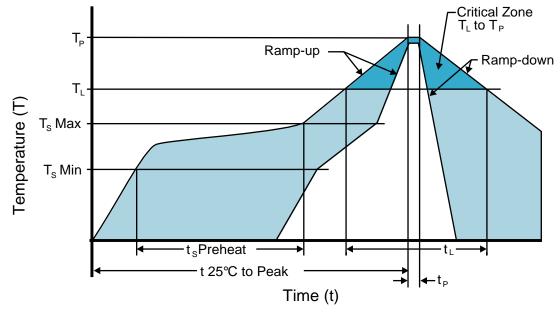


All Tolerances are ±0.1



EC3SMD-12-4.194M

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 225°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T _L to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T _P)	225°C Maximum
Target Peak Temperature (T _P Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t _p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.